

# LNJ826W83RA

## Surface Mounting Chip LED

UTSS Type

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	45	mW
Forward current	$I_F$	20	mA
Pulse forward current *	$I_{FP}$	60	mA
Reverse voltage	$V_R$	4	V
Operating ambient temperature	$T_{opr}$	-30 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-40 to +100	$^\circ\text{C}$

Note) \*: The condition of  $I_{FP}$  is duty 10%, pulse width 10 ms.

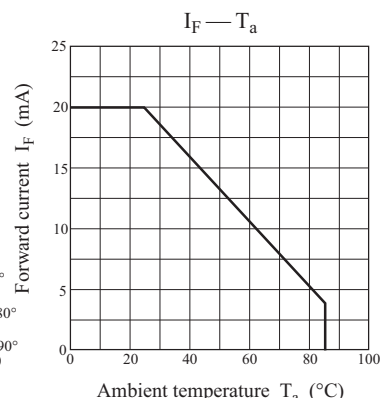
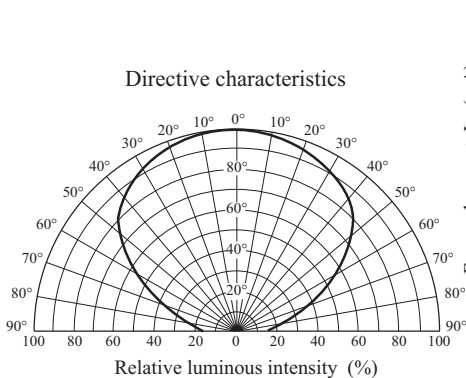
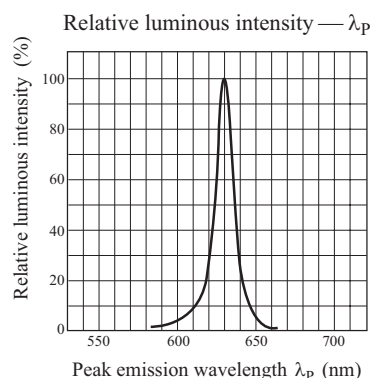
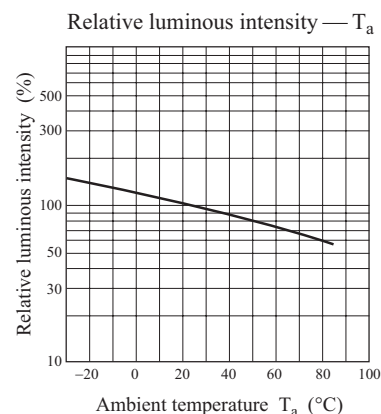
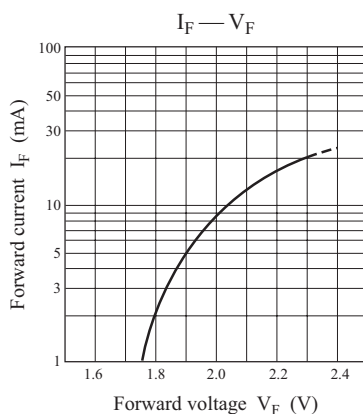
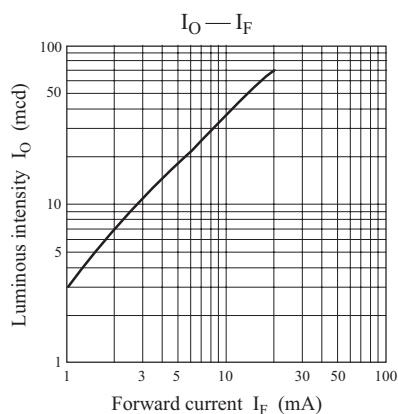
### ■ Lighting Color

- Orange

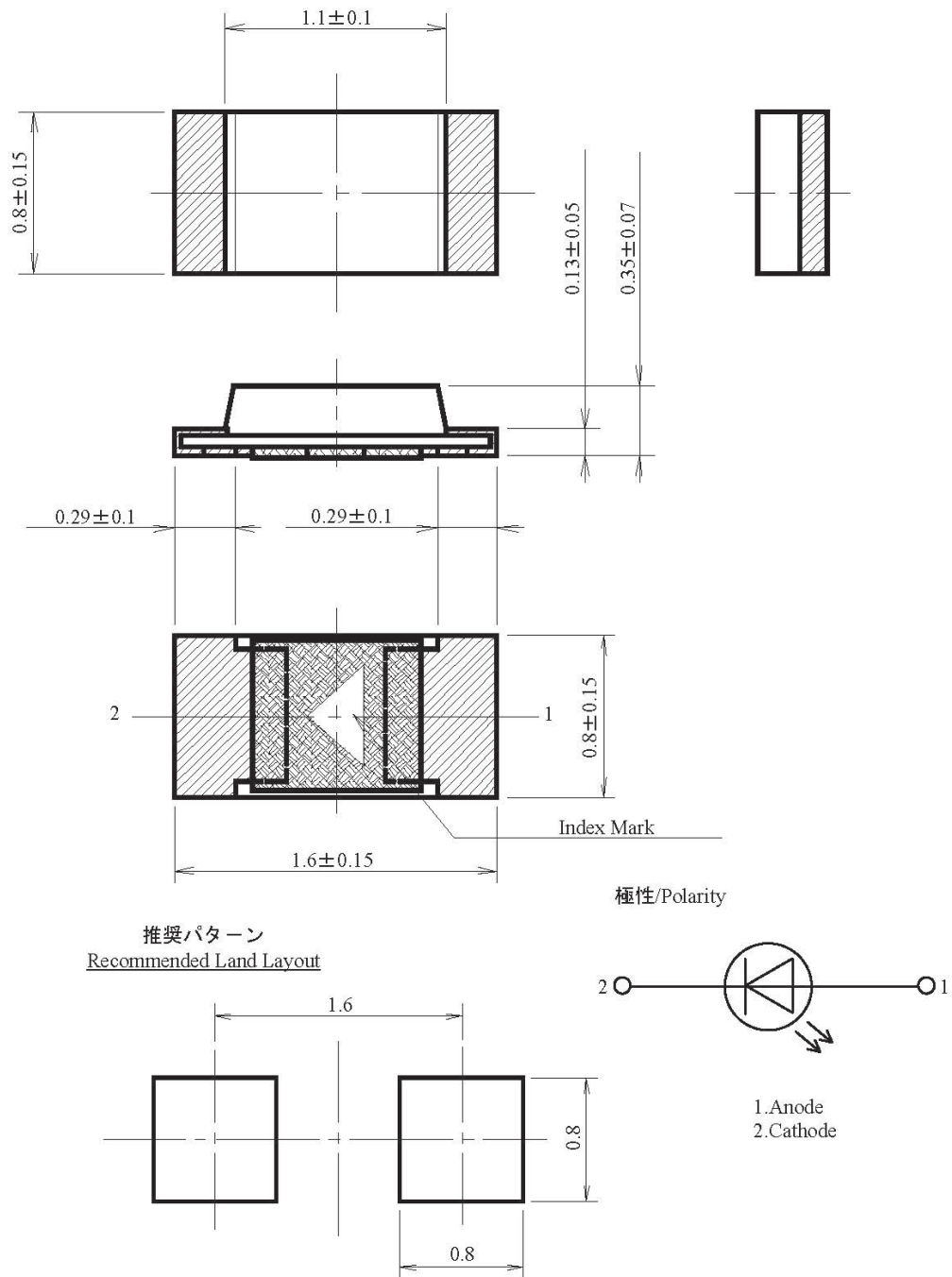
### ■ Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	$I_O$	$I_F = 5\text{ mA}$	11.5	19.0	47.3	mcd
Reverse current	$I_R$	$V_R = 4\text{ V}$			100	$\mu\text{A}$
Forward voltage	$V_F$	$I_F = 5\text{ mA}$		1.9	2.1	V
Peak emission wavelength	$\lambda_P$	$I_F = 5\text{ mA}$		630		nm
Dominant emission wavelength	$\lambda_d$	$I_F = 5\text{ mA}$	615	620	627	nm
Spectral half band width	$\Delta\lambda$	$I_F = 5\text{ mA}$		13		nm

Note) Be careful of the product destruction by static electricity.



■ Package (Unit: mm)



注記/Notes

1. パッケージ寸法については電極バリを含まない。  
Measurement of the package doesn't include electrode projection.
2. 単位:mm/Unit : mm

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